

The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements



A

B

C

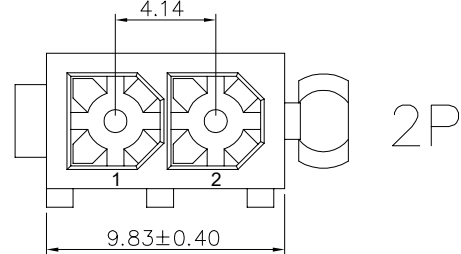
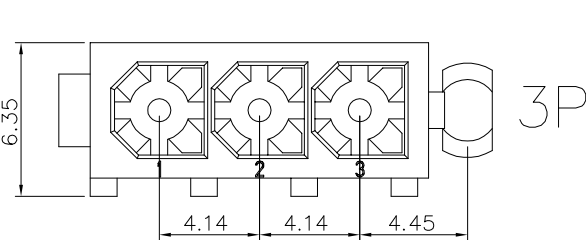
D

E

F

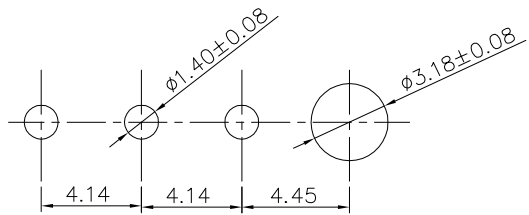
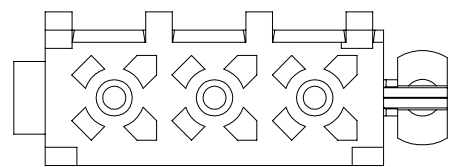
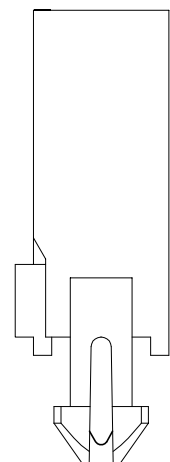
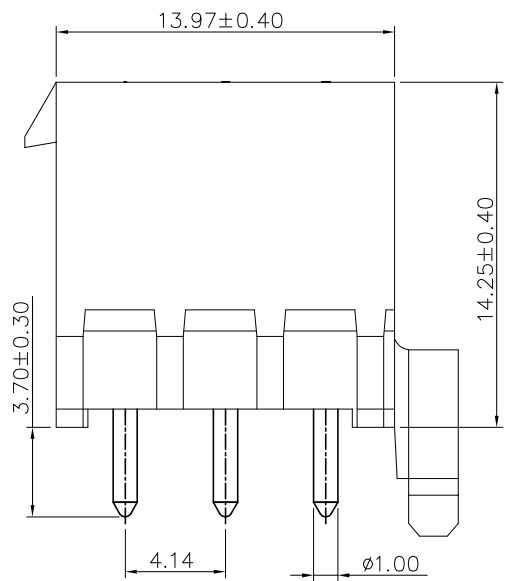
G

H

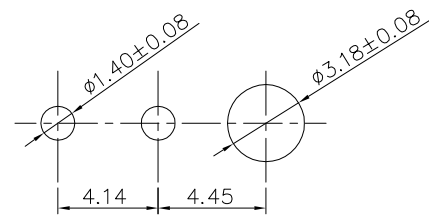


NOTE:
1.MATERIAL SPECIFICATION:
1-1.HOUSING: PA66
1- 2.CONTACTS BRASS
2.PLATING SPECIFICATION:
2-1.CONTACTS:
TIN/GOLD FLASH PLATED OVER ALL.
3.ELECTRICAL PERFORMANCE:
3-1.CURRENT RATING: 7A
RATED VOLTAGE : 600V
3-2.CONTACT RESISTANCE: 20 mΩ MAX
3-3.INSULATION RESISTANCE: 1000MΩ Min
3-4.DIELECTRIC WITHSTANDING : 1500V AC
4.ENVIRONMENTAL PERFORMANCE:
4-1.OPERATING TEMPERATURE: -25°C~+85°C.
5.PACKAGE SPEC PE BAG
6.P/N:

SERIES NO: C4140 W 0-1 XX 1 X X X
CONNECTOR: W-WAFER
ANGLE: 0-180°
9-90°
ROW NO: 1-SINGLE ROW
PIN Q'PY: 02~03
HOUSING: 0-UL94V-0
COLOR: A-BLACK
S-NATURE
PLATING: C-BRIGHT TIN
TERMIPOINT: 1-DIP



RECOMMENDED LAYOUT FOR 1.57 THICK BOARD
TOLERANCES NON-ACCUMULATIVE



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REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO: C4140W0-1XX1XXX	DWG.NO: ENDE05	 WanLian Technology Co., Ltd
AO	NEW RELEASE	21.11.17		LINEAR	ANGLES	APPROVED	Wang_jr	21.11.17			
				0.0±0.35	X°REF±6°						
			UNIT: mm	0.00±0.25	X°±3°	DESIGNER	Han_Gao	21.11.17	TITLE: Pitch 4.14mm 单排 180° DIP Wafer 带定位柱		
			SIZE: A4	0.000±0.10	X°X' ±2°	DRAWN	Zijun_Huang	21.11.17			
										REV: AO	SHEET: 1/1